

SOT403-1

plastic, thin shrink small outline package; 16 leads; 0.65 mm pitch, 5 mm x 4.4 mm x 1.1 mm body

10 December 2019

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	TSSOP16
Package style descriptive code	TSSOP (thin shrink small outline package)
Package body material type	P (plastic)
JEDEC package outline code	MO-153
Mounting method type	S (surface mount)
Issue date	10-12-2019
Manufacturer package code	SOT403-1

Table 1. Package summary

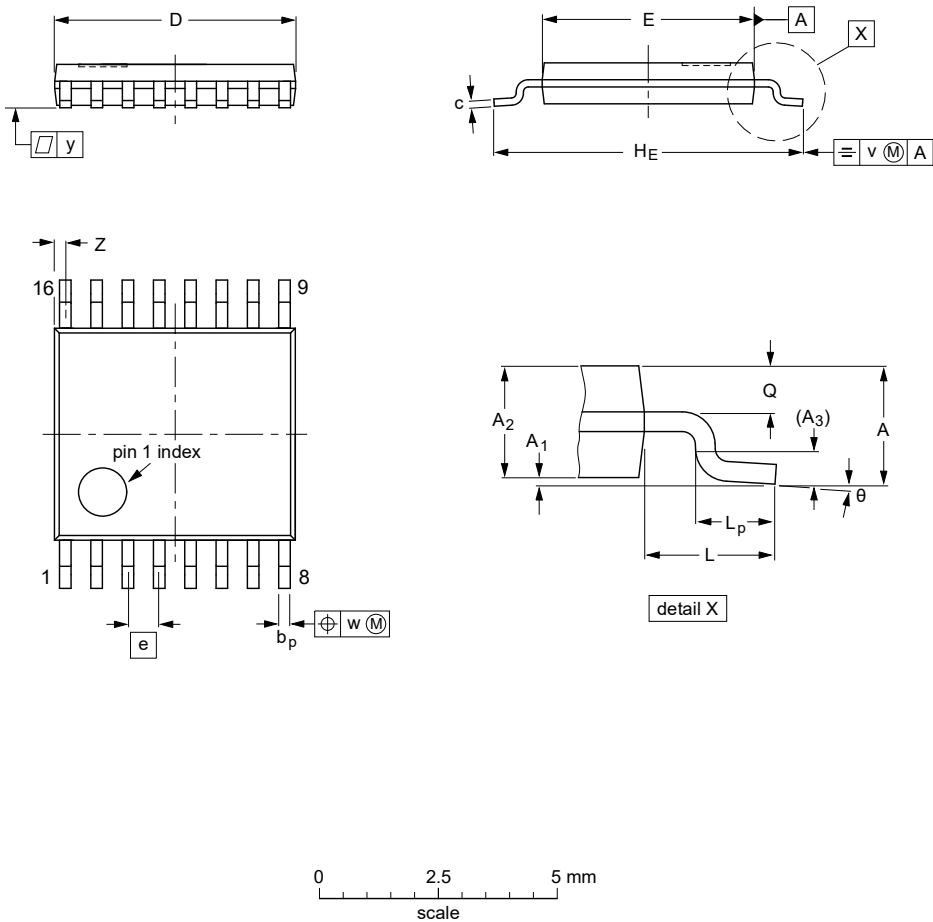
Parameter	Min	Nom	Max	Unit
package length	4.9	5	5.1	mm
package width	4.3	4.4	4.5	mm
seated height	-	-	1.1	mm
package height	0.8	0.9	0.95	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	16	-	



plastic, thin shrink small outline package; 16 leads; 0.65 mm pitch, 5 mm x 4.4 mm body

2 Package outline

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm SOT403-1



DIMENSIONS (mm are the original dimensions)

UNIT	A _{max.}	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.40 0.06	8° 0°

- Notes**
- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
 - 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT403-1		MO-153				99-12-27 03-02-18

Figure 1. Package outline TSSOP16 (SOT403-1)

plastic, thin shrink small outline package; 16 leads; 0.65 mm pitch, 5 mm x 4.4 mm x 1.1 mm body

3 Soldering

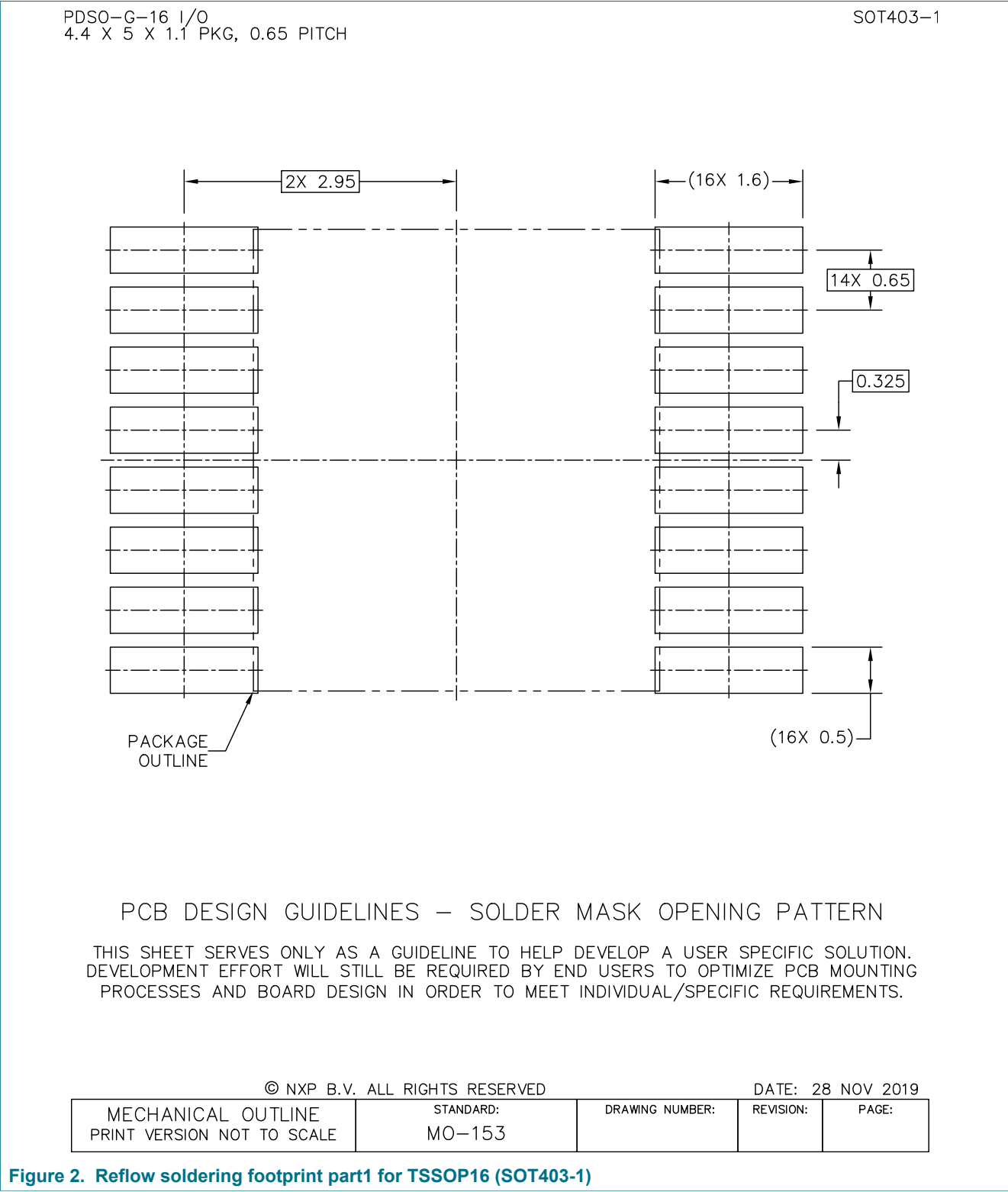
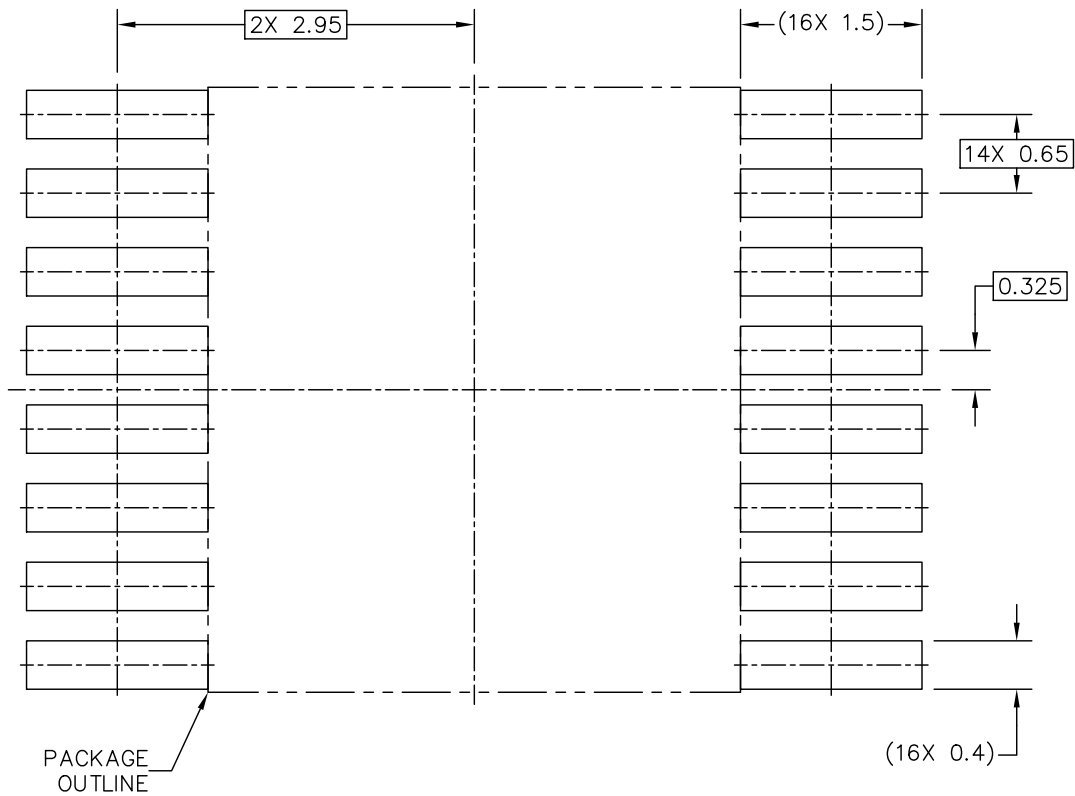


Figure 2. Reflow soldering footprint part1 for TSSOP16 (SOT403-1)

plastic, thin shrink small outline package; 16 leads; 0.65 mm pitch, 5 mm x 4.4 mm x 1.1 mm body

PDSO-G-16 I/O
4.4 X 5 X 1.1 PKG, 0.65 PITCH

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PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

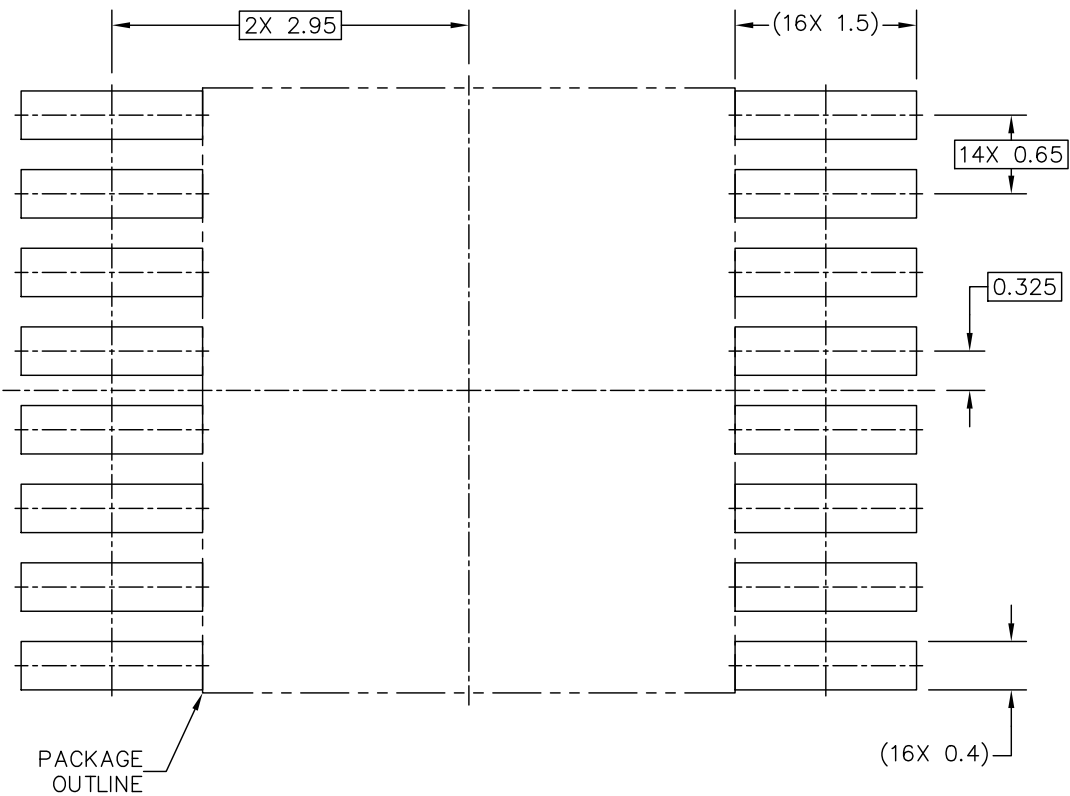
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Figure 3. Reflow soldering footprint part2 for TSSOP16 (SOT403-1)

PDSO-G-16 I/O
4.4 X 5 X 1.1 PKG, 0.65 PITCH

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RECOMMENDED STENCIL THICKNESS 0.125 OR 0.150

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 4. Reflow soldering footprint part3 for TSSOP16 (SOT403-1)

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